

2SJ517

Silicon P Channel MOS FET

REJ03G0874-0400

(Previous: ADE-208-575B)

Rev.4.00 Sep 07, 2005

Description

High speed power switching

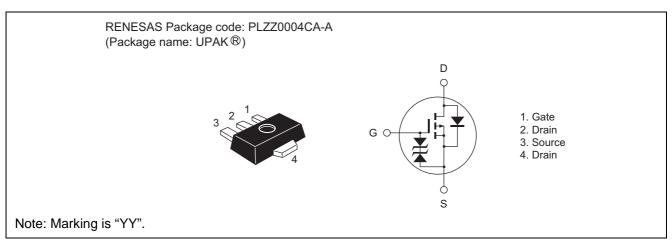
Features

Low on-resistance

$$R_{\text{DS (on)}} = 0.18~\Omega$$
 typ. (at $V_{\text{GS}} = -4~V,~I_{\text{D}} = -1~A)$

- Low drive current
- High speed switching
- 2.5 V gate drive devices.

Outline



*UPAK is a trademark of Renesas Technology Corp.

Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V_{DSS}	-20	V
Gate to source voltage	V_{GSS}	±10	V
Drain current	I _D	-2	A
Drain peak current	I _{D (pulse)} Note 1	-4	A
Body to drain diode reverse drain current	I _{DR}	-2	Α
Channel dissipation	Pch Note 2	1	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 100 μ s, duty cycle \leq 10%

2. When using the aluminium ceramic board (12.5 \times 20 \times 0.7 mm)

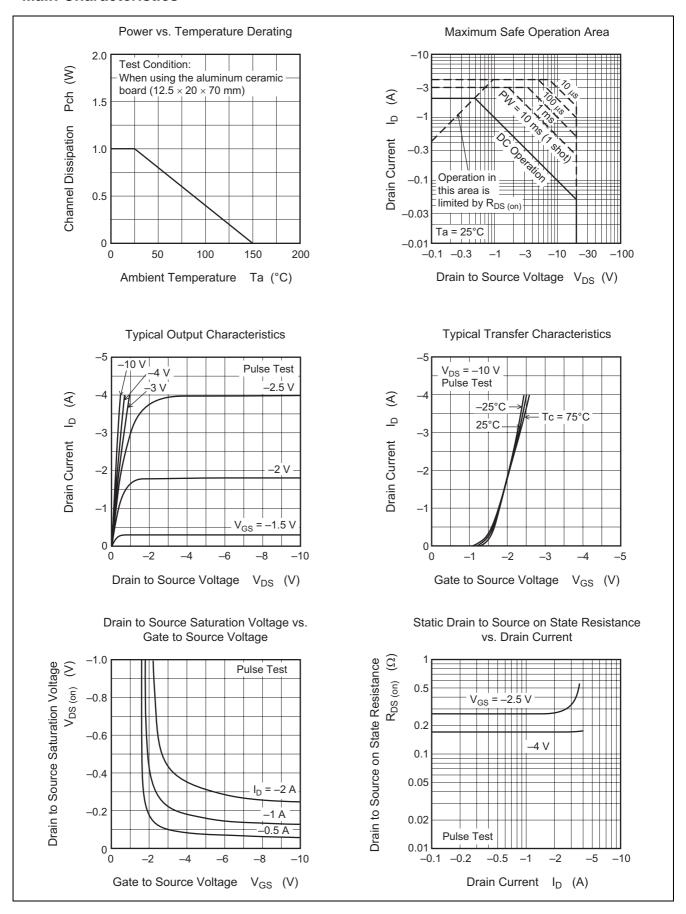
Electrical Characteristics

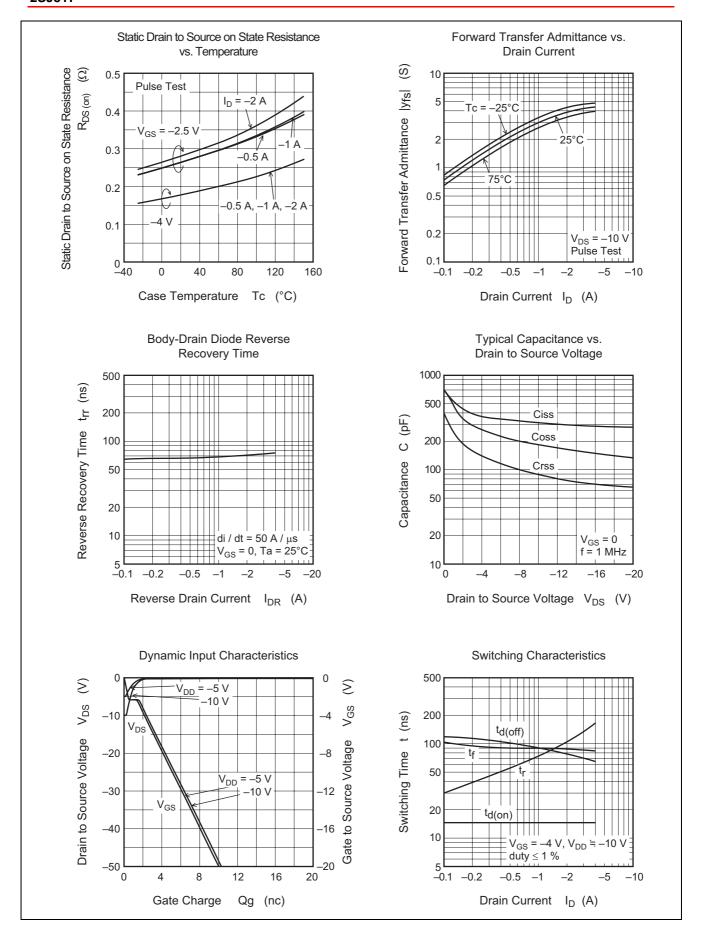
 $(Ta = 25^{\circ}C)$

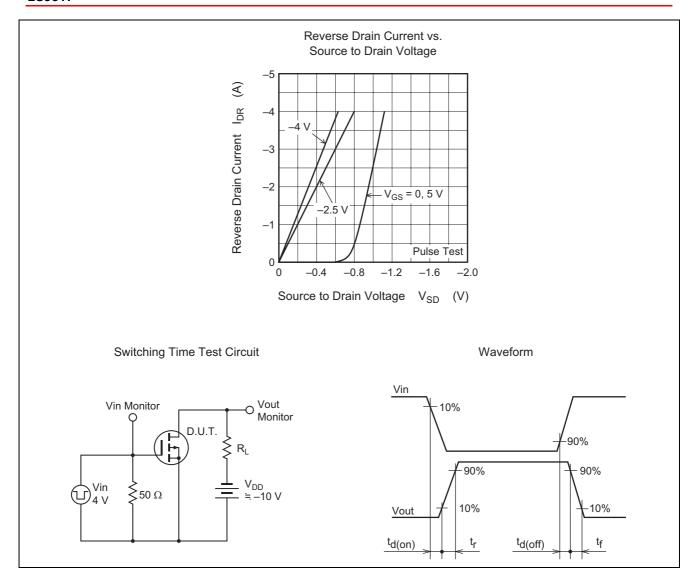
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	-20	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR) GSS}	±10	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	-10	μΑ	$V_{DS} = -20 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	-0.5	_	-1.5	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	R _{DS (on)}	_	0.18	0.24	Ω	$I_D = -1 \text{ A}, V_{GS} = -4 \text{ V}^{\text{Note 3}}$
	R _{DS (on)}	_	0.27	0.43	Ω	$I_D = -1 \text{ A}, V_{GS} = -2.5 \text{ V}^{\text{Note 3}}$
Forward transfer admittance	y _{fs}	1.8	3.0	_	S	$I_D = -1 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss	_	320	_	pF	$V_{DS} = -10 \text{ V}$
Output capacitance	Coss	_	190	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	90	_	pF	f = 1 MHz
Turn-on delay time	t _{d (on)}	_	14	_	ns	$V_{GS} = -4 V$
Rise time	t _r	_	75	_	ns	$I_D = -1 A$
Turn-off delay time	t _{d (off)}	_	90	_	ns	$R_L = 10 \Omega$
Fall time	t _f	_	90	_	ns	
Body to drain diode forward voltage	V_{DF}	_	-0.95	_	V	$I_F = -2 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery	t _{rr}	_	70	_	ns	$I_F = -2 \text{ A}, V_{GS} = 0$
time						$di_F/dt = 50 A/\mu s$

Note: 3. Pulse test

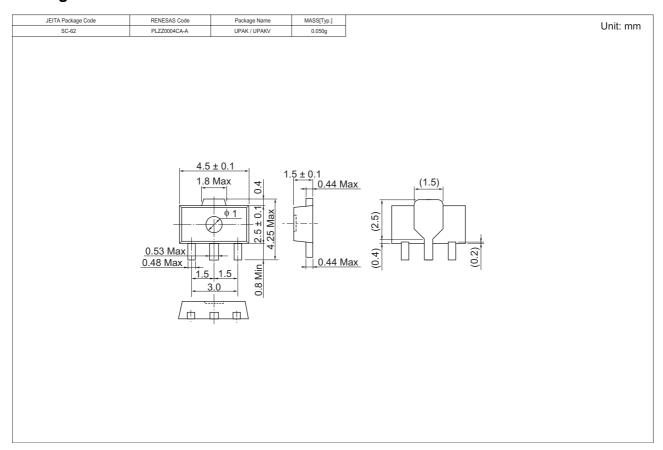
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SJ517YYTL-E	1000 pcs	Taping
2SJ517YYTR-E	1000 pcs	Taping

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